

# MSKSEMI

SEMICONDUCTOR



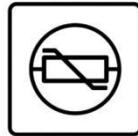
ESD



TVS



TSS



MOV



GDT



PLED

Product data sheet

### Features

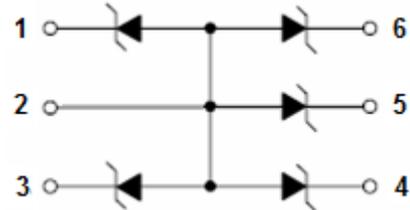
- Small SOT-363 SMT Package
- Peak Power Dissipation 100W @8 x 20 us Pulse
- Low Leakage Current < 1uA @3 Volts
- Fast Response Time < 1 ns
- Low Capacitance
- ESD Protection to IEC 61000-4-2 Level 4
- RoHS Compliant in Lead-Free Versions

**SOT363**



### Applications

- Instrumentation Equipment
- Serial and Parallel Ports
- Microprocessor Based Equipment
- Notebooks, Desktops, Servers



### Electrical Characteristics

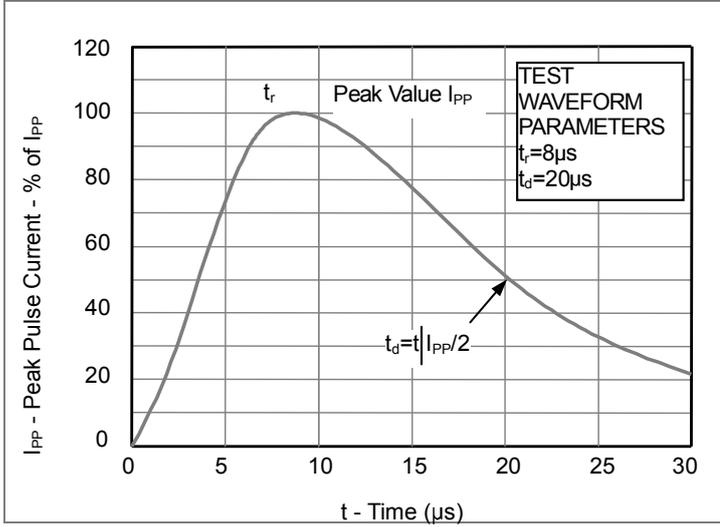
Ratings at 25°C ambient temperature unless otherwise specified.

P/N	Marking	V <sub>RWM</sub> (V)	V <sub>BR</sub> (V)	I <sub>T</sub> (mA)	V <sub>C</sub> @1A	V <sub>C</sub>		I <sub>R</sub> μA (Max)	C (Pf) (Typ.)
						(Max)	(@A)		
SMF05C	5C	5	6	1	9.8	15.5	6.5	1	55

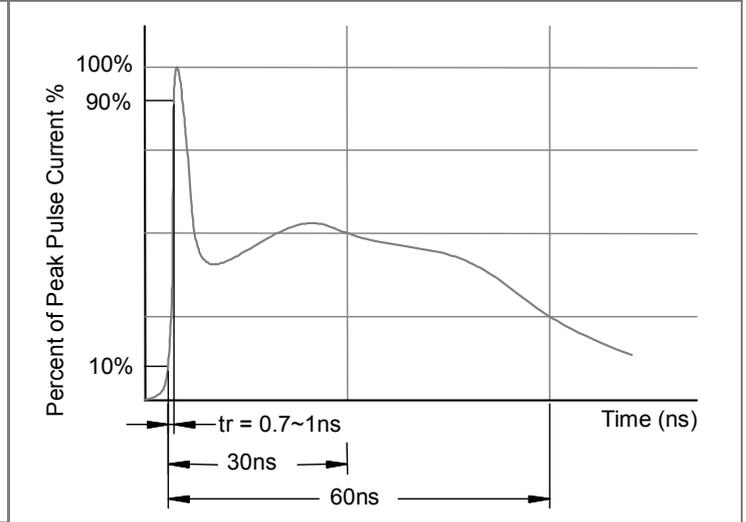
### Absolute Maximum Ratings

Parameter	Symbol	Value	Unit
Peak Pulse Power (8/20μs)	P <sub>pp</sub>	100	W
ESD per IEC 61000-4-2 (Air)	V <sub>ESD</sub>	±15	Kv
ESD per IEC 61000-4-2 (Contact)		±8	
Operating Temperature Range	T <sub>J</sub>	-55 to +125	°C
Storage Temperature Range	T <sub>STJ</sub>	-55 to +150	°C

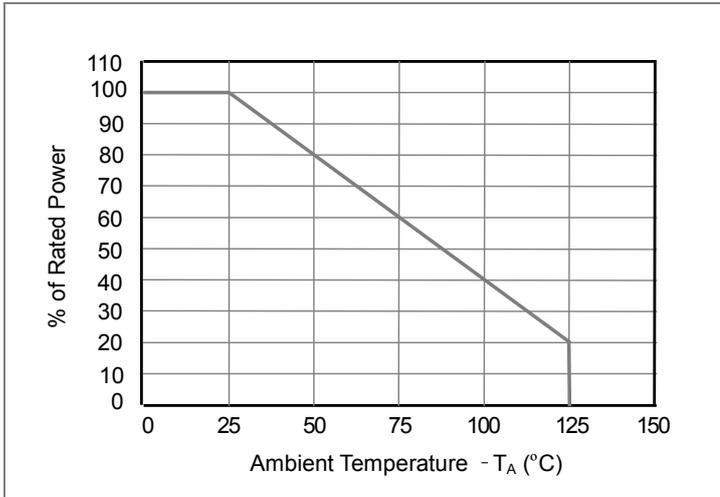
**Fig1. 8/20μs Pulse Waveform**



**Fig2. ESD Pulse Waveform (according to IEC 61000-4-2)**

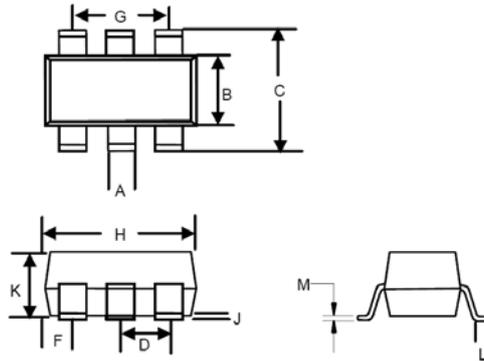


**Fig3. Power Derating Curve**



**Package Dimensions**

**SOT-363**



DIMENSIONS					
DIM	INCHES		MM		NOTE
	MIN	MAX	MIN	MAX	
A	.004	.012	0.10	0.30	
B	.045	.053	1.15	1.35	
C	.079	.087	2.00	2.20	
D	.026		0.65Nominal		
F	.012	.016	0.30	0.40	
H	.071	.087	1.80	2.20	
J	---	.004	---	0.10	
K	.035	.039	0.90	1.00	
L	.010	.016	0.25	0.40	
M	.004	.016	0.10	0.25	

**REEL SPECIFICATION**

P/N	PKG	QTY
SMF05C	SOT-363	3000

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